

Application Report

TPS25830-Q1 Functional Safety FIT Rate, FMD and Pin FMA



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1 Overview

This document contains information for TPS25830-Q1 (VQFN package) to aid in a functional safety system design. Information provided are:

- Functional Safety Failure In Time (FIT) rates of the semiconductor component estimated by the application of industry reliability standards
- Component failure modes and their distribution (FMD) based on the primary function of the device

Figure 1-1 shows the device functional block diagram for reference.

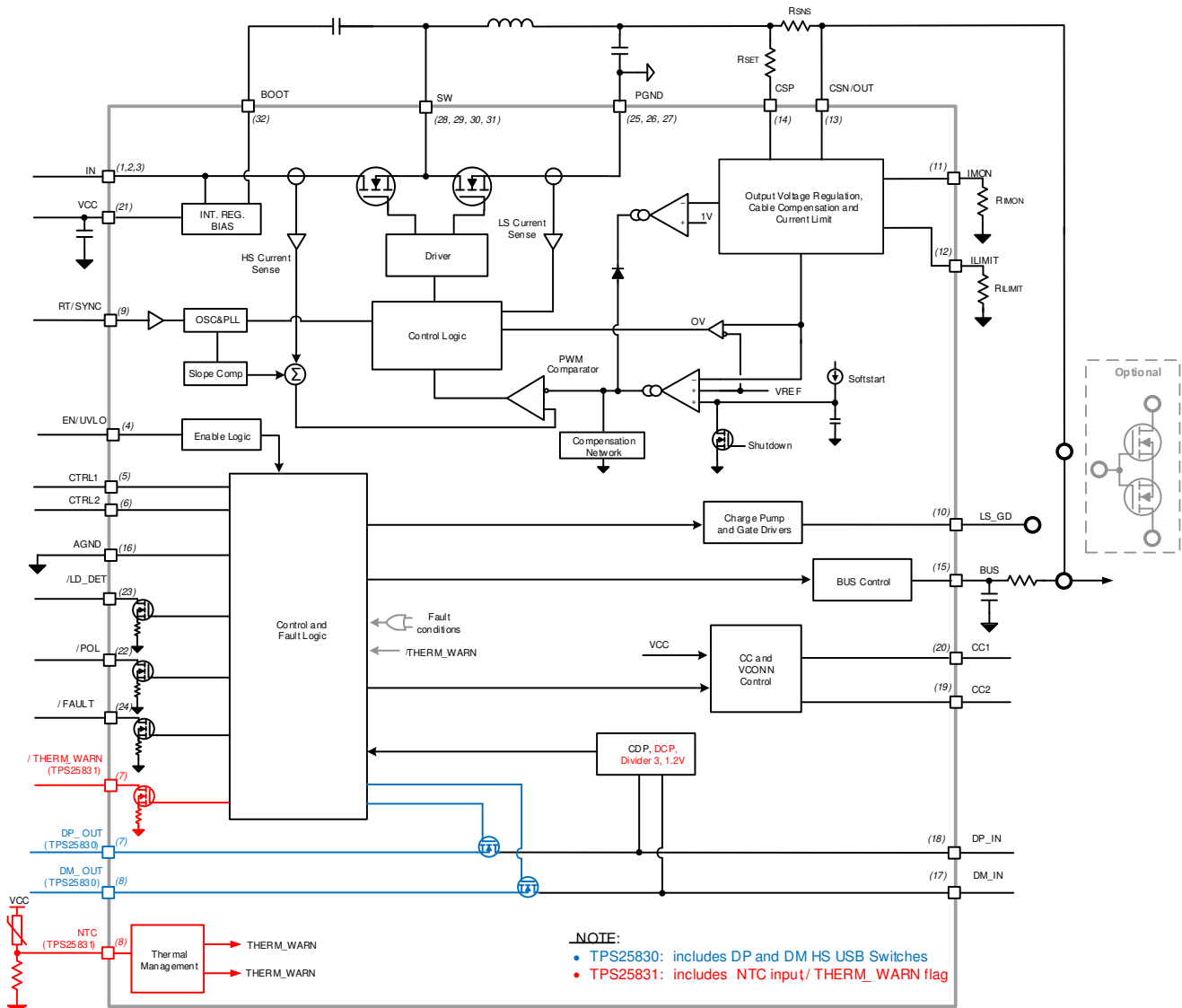


Figure 1-1. Functional Block Diagram

TPS25830-Q1 was developed using a quality-managed development process, but was not developed in accordance with the IEC 61508 or ISO 26262 standards.

2 Functional Safety Failure In Time (FIT) Rates

This section provides Functional Safety Failure In Time (FIT) rates for TPS25830-Q1 based on two different industry-wide used reliability standards:

- [Table 2-1](#) provides FIT rates based on IEC TR 62380 / ISO 26262 part 11
- [Table 2-2](#) provides FIT rates based on the Siemens Norm SN 29500-2

Table 2-1. Component Failure Rates per IEC TR 62380 / ISO 26262 Part 11

FIT IEC TR 62380 / ISO 26262	FIT (Failures Per 10 ⁹ Hours)
Total FIT Rate	27
Die FIT Rate	8
Package FIT Rate	19

The failure rate and mission profile information in [Table 2-1](#) comes from the Reliability data handbook IEC TR 62380 / ISO 26262 part 11:

- Mission Profile: Motor Control from Table 11
- Power dissipation: 1300 mW
- Climate type: World-wide Table 8
- Package factor (λ_3): Table 17b
- Substrate Material: FR4
- EOS FIT rate assumed: 0 FIT

Table 2-2. Component Failure Rates per Siemens Norm SN 29500-2

Table	Category	Reference FIT Rate	Reference Virtual T _J
5	Digital, Analog, Mixed	25 FIT	55°C

The Reference FIT Rate and Reference Virtual T_J (junction temperature) in [Table 2-2](#) come from the Siemens Norm SN 29500-2 tables 1 through 5. Failure rates under operating conditions are calculated from the reference failure rate and virtual junction temperature using conversion information in SN 29500-2 section 4.

3 Failure Mode Distribution (FMD)

The failure mode distribution estimation for TPS25830-Q1 in [Table 3-1](#) comes from the combination of common failure modes listed in standards such as IEC 61508 and ISO 26262, the ratio of sub-circuit function size and complexity and from best engineering judgment.

The failure modes listed in this section reflect random failure events and do not include failures due to misuse or overstress.

Table 3-1. Die Failure Modes and Distribution

Die Failure Modes	Failure Mode Distribution (%)
SW no output	25%
CSP and CSN/OUT not in specification – voltage or timing	20%
LS_GD no output	5%
LS_GD not in specification – voltage or timing	5%
DP_IN, DM_IN, DP_OUT, DM_OUT – no output	10%
DP_IN, DM_IN, DP_OUT, DM_OUT – not in specification – voltage or timing	10%
CC1, CC2 no output	5%
CC1, CC2 not in specification – voltage or timing	10%
FAULT, POL, LD_DET false trip or fails to trip	5%
Short circuit any two pins	5%

The FMD in [Table 3-1](#) excludes short circuit faults across the isolation barrier. Faults for short circuit across the isolation barrier can be excluded according to ISO 61800-5-2:2016 if the following requirements are fulfilled:

1. The signal isolation component is OVC III according to IEC 61800-5-1. If a SELV/PELV power supply is used, pollution degree 2/OVC II applies. All requirements of IEC 61800-5-1:2007, 4.3.6 apply.
2. Measures are taken to ensure that an internal failure of the signal isolation component cannot result in excessive temperature of its insulating material.

Creepage and clearance requirements should be applied according to the specific equipment isolation standards of an application. Care should be taken to maintain the creepage and clearance distance of a board design to ensure that the mounting pads of the isolator on the printed-circuit board do not reduce this distance.

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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